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Preparation of Oriented CuInSe₂ Thin Films at Low Substrate Temperature

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CuInSe₂ thin films have been prepared by vacuum evaporation on glass substrate using Cu₂Se and In₂Se₃ powder as evaporation sources.¹ In general, preparation of CuInSe₂ thin films requires substrate temperature of 400-500°C. We have obtained highly preferred oriented CuInSe₂ thin films at substrate temperature above 400°C without assistance of rf plasma. Moreover, we have succeeded to obtain CuInSe₂ thin films at substrate temperature of 300°C with assistance of radio frequency (rf) plasma.

1.INTRODUCTION

CuInSe₂ is one of I-III-VI₂ ternary chalcopylite structured compound semiconductors, and that has attracted interest recently as the absorption material of high efficiency thin film solar cells due to its large optical absorption coefficient and direct energy band gap about 1eV. As techniques for the preparation of CuInSe₂ thin films², three sources co-evaporation,^{3,4} selenization of metal layers,^{5,6} sputtering,⁷ laser abration,⁸ chemical spray pyrolysis⁹ and electrodeposition¹⁰ are known. The former two methods are advantageous from the viewpoint of development of high efficiency solar cells. Accordingly most studies have focused on these two methods recently.

After consideration of social needs such as low cost development and large area deposition, we prepared CuInSe₂ thin films by vacuum evaporation method on glass substrate using Cu₂Se and In₂Se₃ powder as evaporation sources. This method requires no complicated equipment and is hopeful for large area deposition. Moreover, Cu/In ratio in thin films can be controlled by adjustment of ratio of weight of two evaporation sources. By this method, highly preferred oriented CuInSe₂ thin films were obtained. And we have succeeded to prepare preferred oriented films with assistance of rf plasma at relatively low substrate temperature of 300° C.

2.EXPERIMENTAL

The schematic diagram of equipment is shown in Fig.1. CuInSe₂ thin films were prepared by vacuum evaporation method under gas pressure less than

 $3x10^{-5}$ [Torr]. Substrate was Corning7059 glass cleaned with acetone in ultrasonic cleaner and set 21cm above evaporation sources, and was heated varied up to 600°C.

The helical electrode in chamber was set only when using rf plasma. Ar gas was used as plasma production gas at pressure of 5×10^{-4} [Torr]. The rf power was varied up to 600W.

As evaporation sources, Cu_2Se and In_2Se_3 binary powder were used. We put these binaries into molybdenum (Mo) evaporation boat and covered with Mo lids with several holes. Electric current was supplied to Mo boats about 360A. Such large current is necessary to avoid evaporation of metal elements and Se with time difference. Evaporation of two



Fig. 1 Schematic diagram of equipment for preparation of CuInSe₂ thin films



Fig. 2 XRD patterns of films prepared by different evaporation orders

A: Cu₂Se first and In₂Se₃ second B: In₂Se₃ first and Cu₂Se second

sources are not simultaneously but sequentially. Evaporation order of them was chose by comparing the difference of X-ray diffraction(XRD) patterns of films prepared by both evaporation orders. XRD patterns of them are shown in Fig.2. For example, XRD patterns of films prepared at substrate temperature of 600°C without assistance of rf plasma are shown. XRD pattern of film prepared in order of In_2Se_3 first and Cu_2Se second (A) includes not only peaks from CuInSe₂ but also that unknown. On the other hand, pattern of film prepared in the reverse order (B) includes no peak other than that from CuInSe₂ and shows preferred orientation to (112) of CuInSe₂. This result is also obtained in other deposition conditions. Therefore evaporation order of them was Cu₂Se first and In₂Se₃ second.

3.RESULTS AND DISCUSSION

3.1 The cause that influences degree of preferred orientation of CuInSe₂ thin films

XRD patterns of films prepared at the substrate temperature of 300-600°C without assistance of rf plasma are shown in Fig.3(a). Patterns of films







prepared at substrate temperatures above 400° C include no peak other than those from CuInSe₂ and indicate highly preferred orientation to (112) of CuInSe₂. On the other hand, pattern of film prepared at 300°C includes not only peaks from CuInSe₂ but also that from unknown and degree of preferred orientation is inferior to those of films prepared above 400°C.

And we prepared films by evaporating of each binaries, Cu₂Se and In₂Se₃, individually under the same deposition conditions that for preparation of CuInSe₂ thin films. From XRD patterns of these films, it is observed that films prepared by evaporation of In₂Se₃ did not crystallize, on the other hand, those of Cu₂Se crystallized. XRD patterns of films prepared by evaporation of Cu₂Se under the same conditions of CuInSe₂ in Fig.3(a) are shown in Fig.3(b). Pattern of film prepared at 300°C includes peaks from both of Cu₂Se and Cu_{2-x}Se, but pattern of film prepared at 600°C shows highly preferred orientation to (030) of Cu₂Se. This tendency of preferred orientation is very similar to that of Fig.3(a). Therefore, we consider that degree of preferred orientation of CuInSe₂ thin films depends on that of Cu₂Se thin films.

3.2 Lowering substrate temperature for preparation of CuInSe₂ thin films

From the results described above, we employed rf plasma during evaporation of both binary sources to improve degree of preferred orientation of Cu₂Se thin films at 300°C in order to improve that of CuInSe₂ thin films. XRD patterns of films prepared by evaporating of Cu₂Se at 300°C with assistance of rf plasma are shown in Fig.4(a). Cu_2Se thin film which indicates preferred orientation is obtained at 300°C with assistance of rf plasma at power of 400W. And XRD patterns of films prepared by evaporating of Cu₂Se and In₂Se₃ at 300°C with assistance of rf plasma are shown in Fig.4(b). Preferred orientated CuInSe₂ thin film was obtained at 400W. From this results, it is clear that use of rf plasma during evaporation is very effective to improve degree of orientation of CuInSe₂ thin films. The scanning electron microscope (SEM, HITACHI S-4500) image of thin film is shown in Fig.5. The structure with large grains tightly arranged is observed.

As the method to improve degree of orientation of $CuInSe_2$ thin films at low substrate temperature, we



Fig.4 XRD patterns of films prepared with assistance of rf plasma by evaporating of (a)Cu₂Se only (b)Cu₂Se and In₂Se₃

prepared CuInSe₂ thin films by setting interval between evaporation of Cu₂Se and In₂Se₃ in order to obtain preferred orientated Cu₂Se thin films at lower substrate temperature. XRD pattern of film prepared at the substrate temperature of 200°C with interval of



Fig.5 SEM image of CuInSe₂ thin film prepared at 300°C with assistance of rf plasma at 400W



Fig.6 XRD pattern of film prepared at 200°C with interval of 4min.



Fig.7 SEM image of CuInSe₂ thin film prepared at 200°C with interval of 4min.

4min. between evaporation of two sources without assistance of rf plasma is shown in Fig.6. This pattern includes only peaks from CuInSe₂, and indicates preferred orientation to (112) of CuInSe₂. By this method, highly orientated CuInSe₂ thin film have been obtained at such a low substrate temperature as 200°C. The SEM image of this film is shown in Fig.7. The structure with smaller grains than the film prepared at 300°C with assistance of rf plasma at 400W is observed.

4.CONCLUSION

Highly orientated CuInSe₂ thin films were prepared at substrate temperature of 300° C with assistance of rf plasma at power of 400W by using the result that degree of preferred orientation of CuInSe₂ thin films depends on that of Cu₂Se thin films. The structure with large grains tightly arranged is observed. By setting interval between evaporation of two sources, preferred orientated CuInSe₂ thin film was obtained at substrate temperature of 200°C with small grains.

REFERENCES

- 1 A.Ashida, Y.Hachiuma, N.Yamamoto, T.Ito and Y.Cho: Jpn. J. Appl. Phys. **32** (1993) Suppl. 32-3, pp.84-85.
- 2 B.M.Basol: Jpn. J. Appl. Phys. **32** (1993) Suppl. 32-3, pp.35-40.
- 3 T.Walter and H.W.Shock: Jpn. J. Appl. Phys. **32** (1993) suppl.32-3, pp.116-119.
- 4 N.Kohara, T.Negami, M.Nishitani and T.Wada: Jpn. J. Appl. Phys. **34** (1995) pp.L1141-L1144.
- 5 B.H.Tseng, Y.C.Chang, S.B.Lin and H.L.Hwang: Jpn. J. Appl. Phys. **32** (1993) Suppl. 32-3, pp.88-89.
- 6 M.Tanda, S.Manaka, J.R.Encinas Marin, K.Kushiya, H.Sano, A.Yamada, M.Konagai and K.Takahashi: Jpn. J. Appl. Phys. **31** (1992), pp.L753-L755.
- 7 T.Nakada, K.Migita and A.Kunioka: Jpn. J. Appl. Phys. **32** (1993) Suppl. 32-3, pp.48-49.
- 8 I.Taguchi, H.Ezumi, S.Keitoku, T.Tamaru and H.Osono: Jpn. J. Appl. Phys. **34** (1995) pp.L135-L137
- S.Shirakata, T.Murakami, T.Kariya and
 S.Isomura: Jpn. J. Appl. Phys. 35 (1996) pp.191-199
- 10 Y.Sudo, S.Endo and T.Irie: Jpn. J. Appl. Phys.32 (1993) pp.1562-1567